

Figure 1 is a perspective view of a display device 100. The device includes a display panel 110 with a central display area 112 and a surrounding bezel 111. The bezel 111 is divided into four sections 113, 114, 121, and 122. A camera module 120 is located in the center of the display area 112. The device is mounted on a substrate 130, which has a series of pins 131 along its edges. A bracket 301 is used to secure the device to the substrate.

FIG. 3

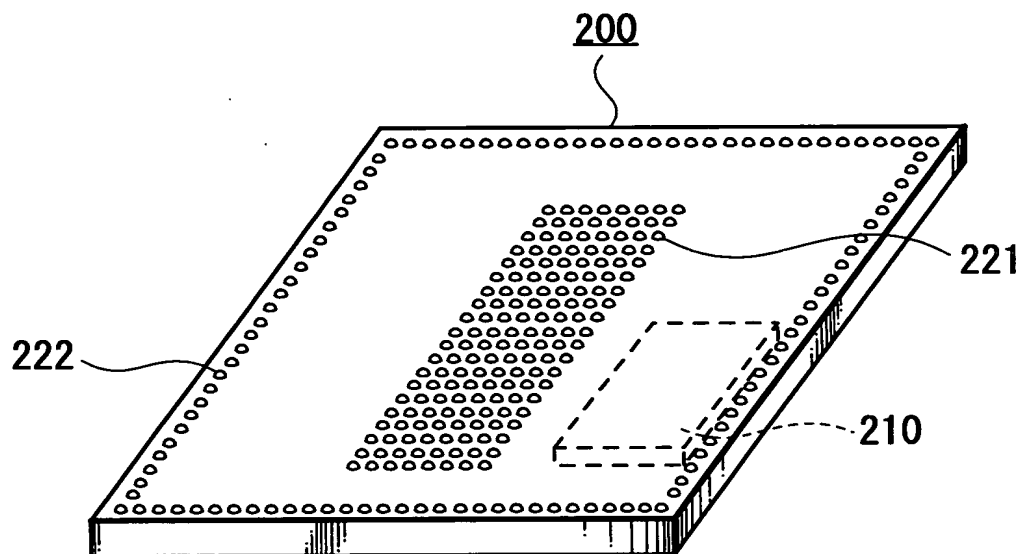


FIG. 4

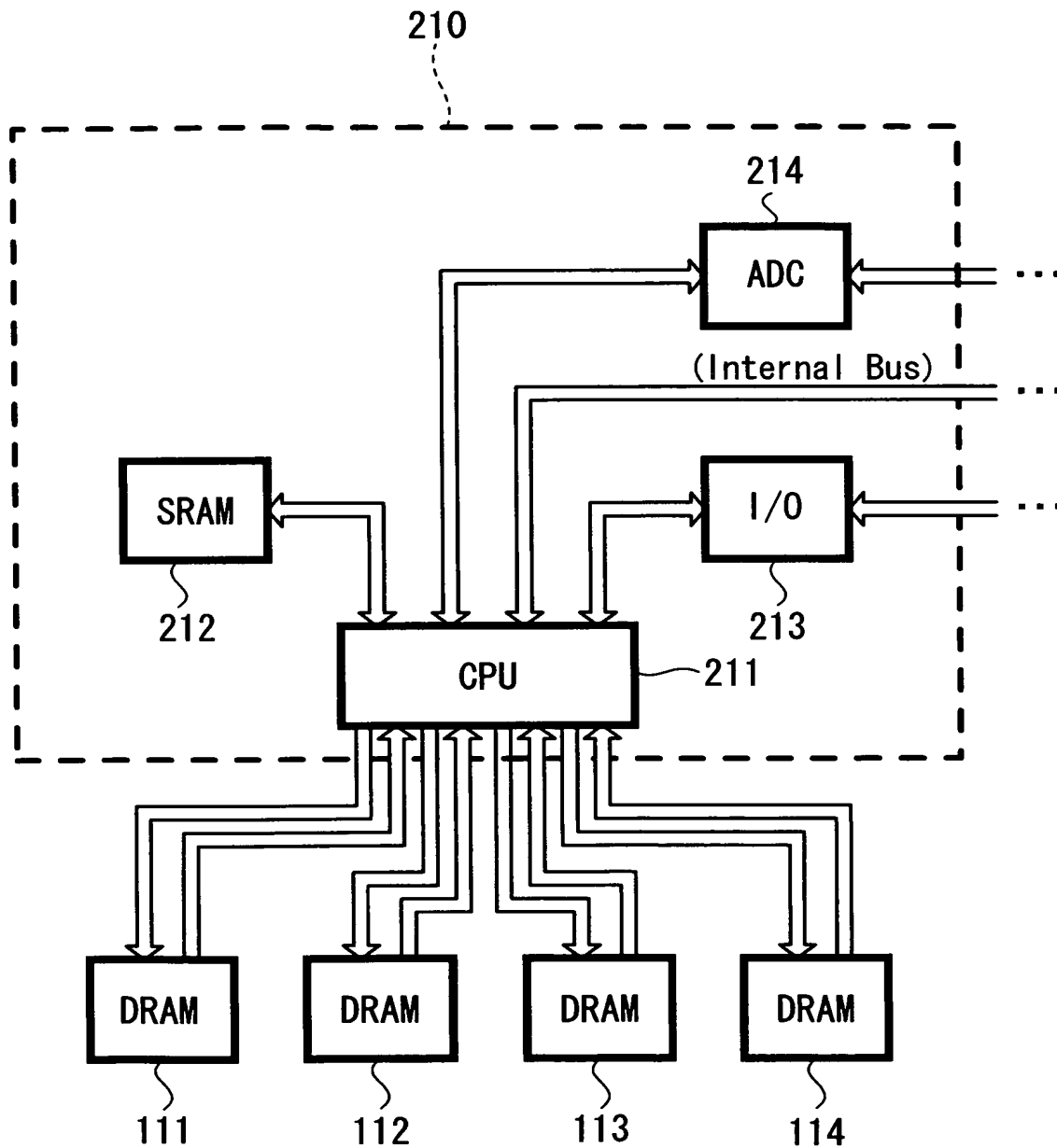


FIG. 5

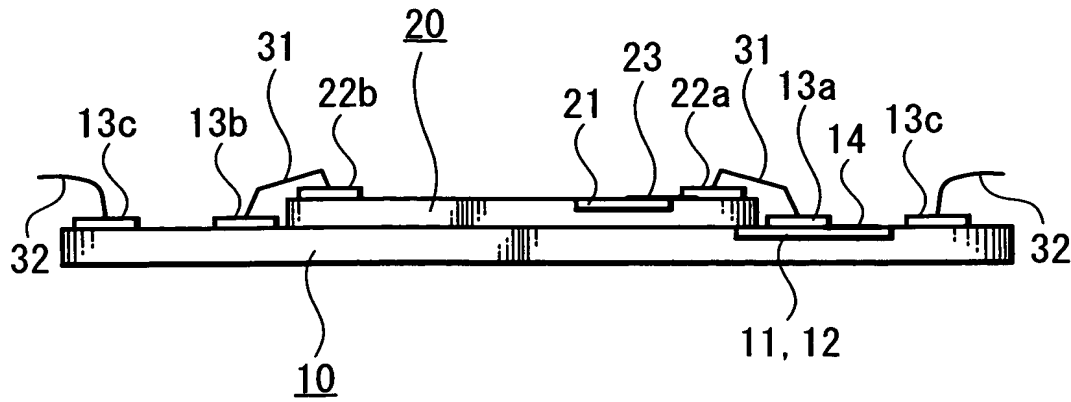


FIG. 6

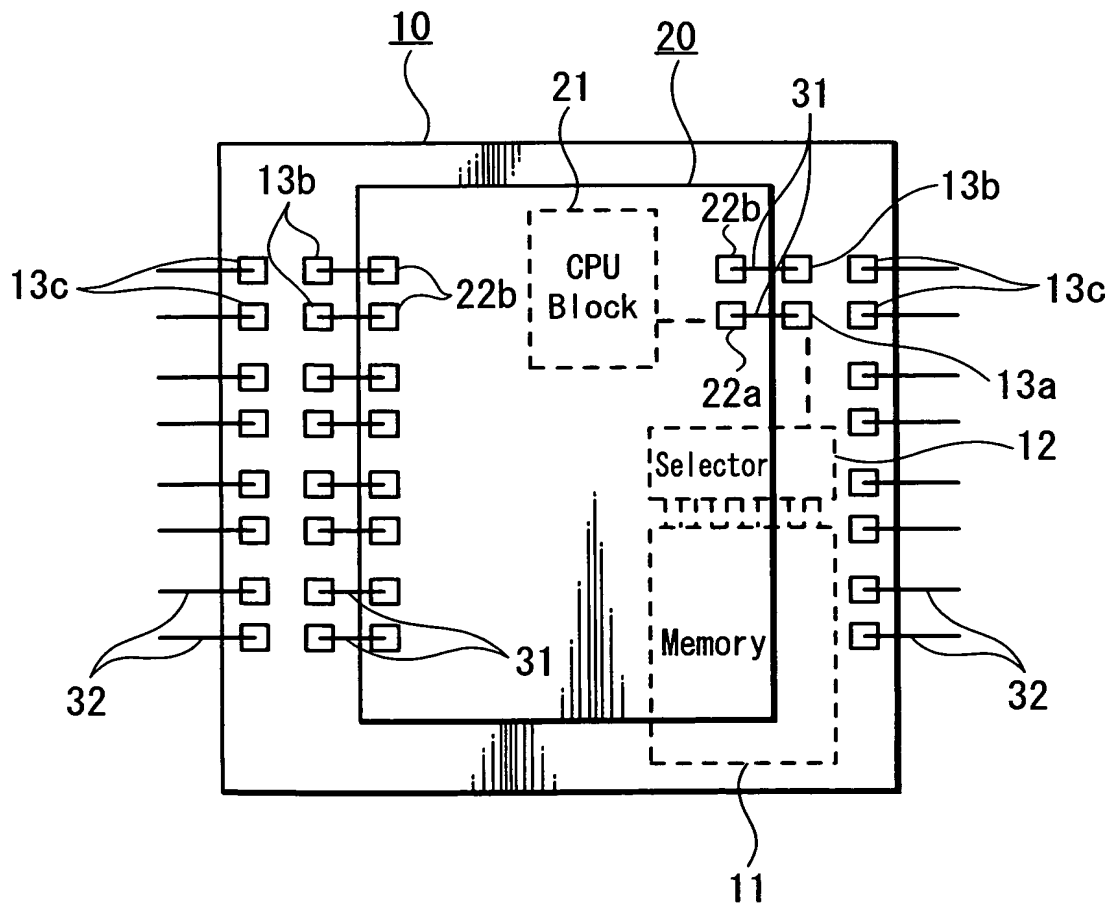
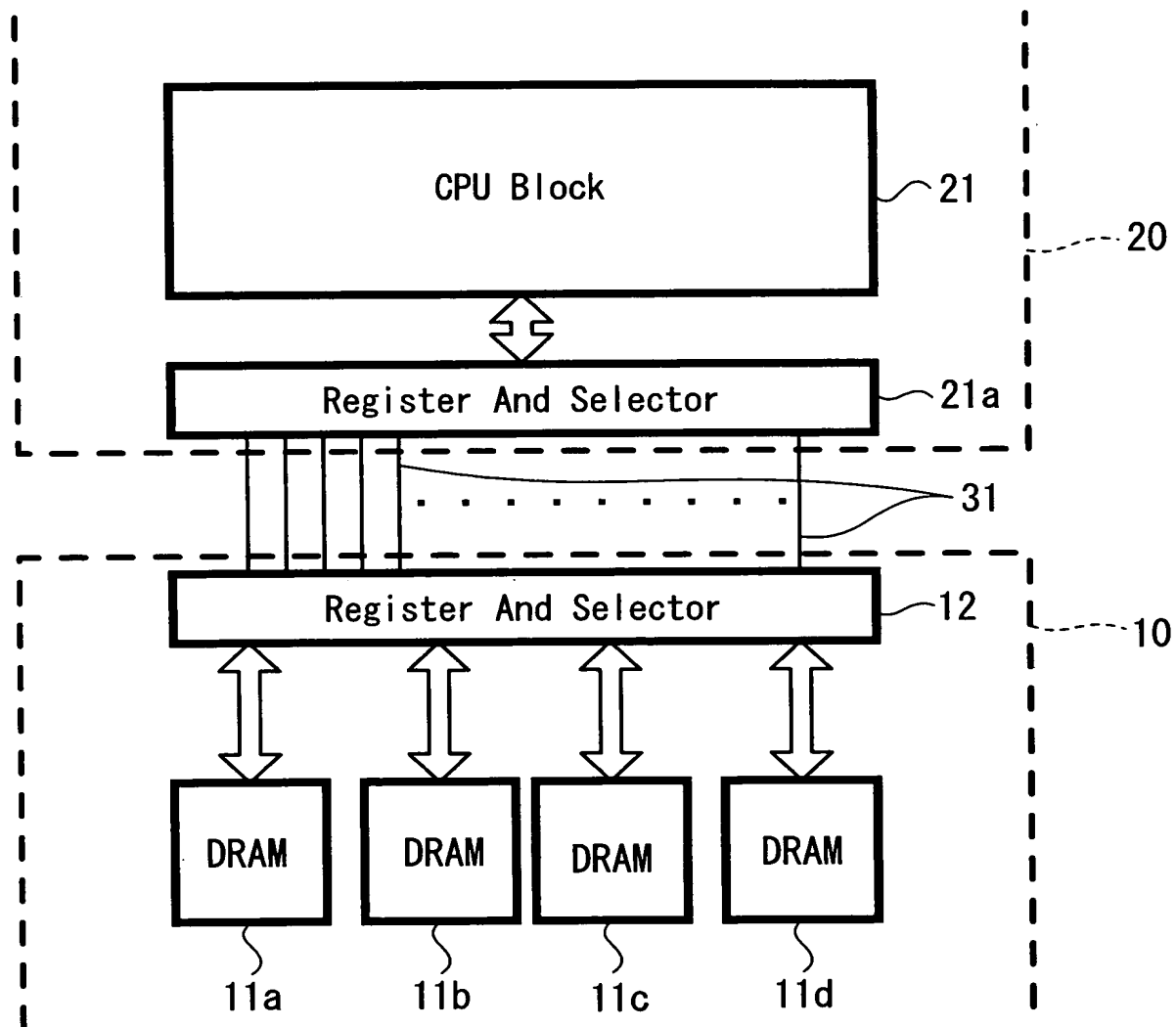


FIG. 7



DESCRIPTION OF REFERENCE NUMERALS

10.....FIRST CHIP

11, 11a to 11d.....DRAM

12.....REGISTER AND SELECTOR

13a to 13c.....PAD

20.....SECOND CHIP

21.....CPU BLOCK

21a.....REGISTER AND SELECTOR

22a, 22b.....PAD

31.....WIRE

100.....FIRST CHIP

101 to 105.....INTERNAL WIRING

111 to 114.....DRAM

121,122.....ELECTRODE HAVING MICRO BUMP

131.....PAD

200.....SECOND CHIP

201 to 105.....INTERNAL WIRING

210.....CPU BLOCK

211.....CPU

212.....SRAM

213.....INTERFACE

214.....ANALOGUE/DIGITAL CONVERTER

221,222.....ELECTRODE HAVING MICRO BUMP

301.....WIRE